



For Immediate Release:

September 19, 2007

**Austin Semiconductor, Inc. announces a Sub-System in Package (SSiP)
Product Family with details of the first SSiP development underway**

Austin, Texas - Austin Semiconductor, Inc. (ASI), a leading supplier of high reliability (HI-REL) as well as, ruggedized plastic encapsulated semiconductor products and services, announces the addition of a new Sub-System in Package (SSiP) product family, as well as the development effort of a Solid State Disk on Chip device grouping, the first members of the SSiP family.

The Austin Semiconductor Sub-System in Package product family will increase the value of the solutions offered to current markets served and open new opportunities within their target expansion markets. The target markets of Embedded/Industrial systems, Heavy Transportation, Ultra portables as well as Handhelds have varying levels of harshness induced and therefore have requirements for harshness tolerant, integrated component solutions. The Solid State Disk on Chip (SSDoC) will be the first product offered, and is currently in development.

The first Solid State Disk on Chip grouping of products will provide end users with a PIDE - mode 4, multi-word DMA - mode 2, Disk drive family with the following features:

- 1.22" square X, Y footprint with maximum heights of 0.220" for our 1GB and 2GB devices, 0.300" for our 4GB device and 0.475" for our 8GB and 16GB devices.
- 381 ball, 1.27mm ball pitch package definition, providing multiple balls per signal, non-straight line (NSL) for improved electro-mechanical interconnect and manufacturability.
- NAND-SLC based Solid State storage.
- Embedded IDE controller w/ATA-IDE interface.
- 512 Byte sectors.
- Flash memory Power-Down logic.
- ECC correction, 6 bytes within each 512 Byte sector.
- Automatic Sleep Mode.
- Burst Transfer Rate = 16.67 Mega Bytes per second.
- Sustained Transfer Rate = 7.7 megabytes per second on our 1, 2, 4, and 8 gigabyte drives.
- Sustained Transfer Rate = 5.0 megabytes per second on our 16 gigabyte drive.
- Sophisticated Wear Leveling for extended Drive life.

All SSDoC devices will work with either a 5V or 3.3V power supply and will be initially available in Commercial, Industrial temperature ranges with plans for an Enhanced temperature (-40 to +105C) offering in mid 2008.

Austin Semiconductor's Sub-System in Package roadmaps include additional Solid State Disk on Chip (SSDoC) groupings, including UDMA and SATA definitions as well as complete memory and mixed-signal sub-systems.

This product family is based on embedded packaged devices in multiple organic laminates and is manufactured using a proprietary stacking technology to create an extremely space conscious, robust Solid State Disk Sub-system. [This sub-system therefore is](#) capable of operating in harsh, vibration prone product platforms. Product Flyer is available now, full datasheet expected in November with first article samples due at end of year and full production in Q1-2008.

Austin Semiconductor, Inc. (ASI) is progressively changing the component availability landscape for integrated components, sub-systems and systems in package for use in Hi-Reliability and harsh environments. They will continue an aggressive development plan that will bring added value via integration.

Austin Semiconductor, Inc. (ASI) is a fully QML certified, ISO registered company that supports the high reliability requirements of industries including Military, Aerospace, Transportation, Industrial-Embedded as well as and Medical¹. ASI offers I/C components, Multi-Chip Modules and Integrated product solutions to their customers through a broad line of HI-REL Integrated Plastic Encapsulated Microcircuits (iPEM) as well as Commercial-Off-The-Shelf (COTS) up-screened products. ASI continually adds and maintains many product lines composed of standard & specialty memory and digital & analog solutions. ASI also offers Whole Life Product Support services, aiding it's customers through the technology transitions.

For additional information, contact:
David Harrison, VP of Sales and Marketing
dharrison@austinsemiconductor.com
Direct: 512.719.7251
Mobile:508.380.0495

¹ Diagnostic-Monitoring/Imaging, Non-Life support Medical Applications
###